

Electronic Patent Application Fee Transmittal

Application Number:	10554855
Filing Date:	18-Oct-2006
Title of Invention:	Brittle substrate cutting system and brittle substrate cutting method
First Named Inventor/Applicant Name:	Kenji Otoda
Filer:	Howard I. Sobelman/Julie Eslick
Attorney Docket Number:	49288.1600

Filed as Large Entity

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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130